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*#12 3/1/02*

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: )  
Application No.: 09/741,072 )  
Filed: December 21, 2000 )  
For: WAFER POLISHING HEAD )  
Applicant: Lin et al. )  
Examiner: Dung V Nguyen )  
Art Unit 3723 )

AMENDMENT

Assistant Commissioner of Patents and Trademarks  
Washington, DC 20231

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FEB 27 2002  
TC 3700 MAIL ROOM

Sir:

In response to the Office Action dated October 10, 2001, please enter the following amendments and consider the following remarks.

In The Claims

Please add the following new claims.

12. (New) A wafer polishing head for planarizing a wafer comprising a carrier for loading the wafer, a wafer adhering layer disposed beneath the carrier, a retaining ring surrounding the carrier and the wafer adhering layer, the wafer polishing comprising:

a first pressure chamber having a first inner pressure disposed above the retaining ring;

a second pressure chamber having a second inner pressure disposed on the carrier; and

an automatic control system respectively coupled to the first pressure chamber and the second pressure chamber for adjusting a relative height between the carrier and the retaining ring.

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